

# Failure Analysis Lab

## Root Cause Analysis With State-Of-The-Art High-Resolution Tools & Techniques

### For Non-destructive Inspection & Failure Analysis

#### 2D/3D X-Ray & CT Scan Imaging

- Digital X-ray with < 100nm feature recognition
- Digital Zoom up to 35,500X
- Defect detection using 3D Image Sectioning
- Automated X-ray void detection & measurement

#### Infrared Thermal Imaging

- 320 x 240 pixel live IR image resolution
- 3.1 Mega-pixel visible spectrum picture-in-picture
- Real-time data acquisition and analysis

#### Digital Microscopy

- Extremely high resolution up to 20,000 x 20,000 pixels
- 0.1x to 5000x magnification
- 3D surface modeling

#### Stress Testing

##### (Thermal & Vibration)

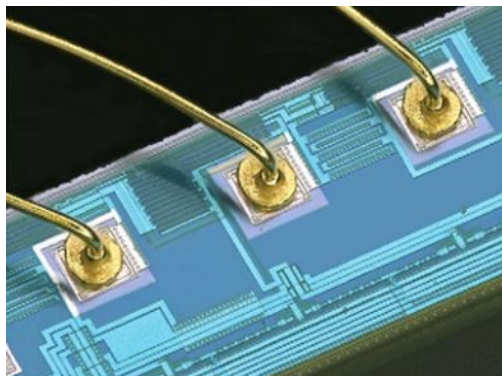
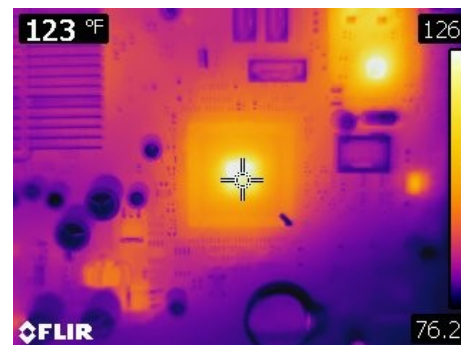
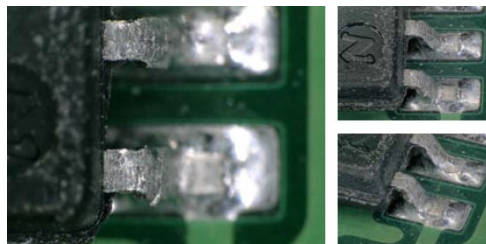
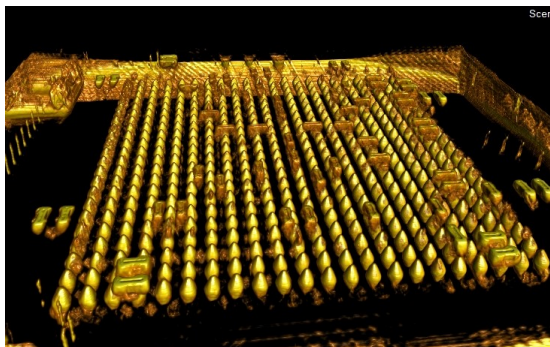
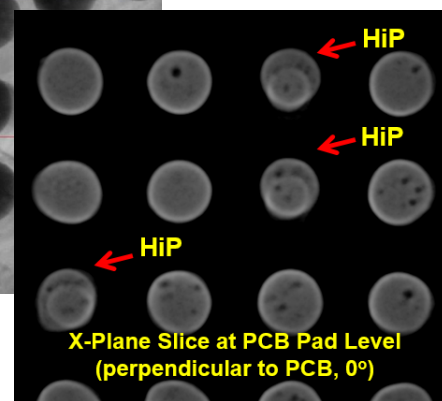
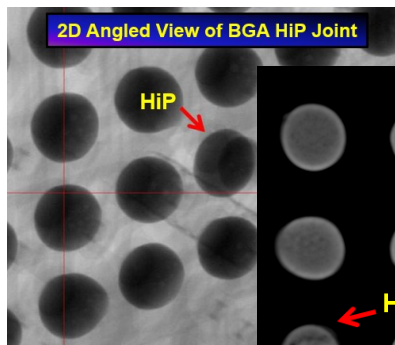
Vibration and Thermal (-80°C to +225°C) are compliant with all DO-160G requirements

#### Advanced Failure Analysis

Utilizing proprietary analysis method

#### Benefits

- Reduce production problems
- Reduce NFF returns
- Identify mechanical root cause
- Improve designs
- Reduce cost
- Quick Turnaround
- Increase yields



#### Markets Served

- Aerospace
- Space
- Microelectronics
- Industrial
- Medical
- Consumer
- Engineering and R&D
- Product Support